

CLEAN COPY OF CLAIMS:

B1
1. (Twice Amended) A semiconductor device comprising:
a first semiconductor chip consisting of at least either a circuit against static damage or a passive component;
a second semiconductor chip and a third semiconductor chip installed on a support substrate, wherein said second semiconductor chip and said third semiconductor chip are connected with each other through said first semiconductor chip; and
wherein said second semiconductor chip is a DRAM chip, and said third semiconductor chip is a logic chip.

B2
4. (Twice Amended) A semiconductor device comprising:
a semiconductor chip consisting of only a passive component, said passive component includes all of a resistor, a capacitor and a reactor.

B3
6. (Amended) The semiconductor device according to claim 1, wherein
said second semiconductor chip and said third semiconductor chip include no circuits against static damage.